

**LINEAR TECHNOLOGY MATERIALS DECLARATION**

1t1781isw#trpbf

(Engineering Calculation)

SOIC WIDE

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**TOTAL MASS (g) : 0.248781**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.004106	1000000	16504.4511719		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.138021	975000	554788.375		
		Iron (Fe)	7439-89-6	0.003397	24000	13654.5595703		
		Phosphorus (P)	7723-14-0	0.000042	300	168.822921753		
		Zinc (Zn)	7440-66-6	0.000099	700	397.939758301		
		Nickel (Ni)	7440-02-0	0.000000	0	0		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
<b>Lead Frame Total:</b>				<b>0.141559</b>	<b>1000000</b>	<b>569009.6875</b>		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.004771	1000000	19178.9609375		
		<b>External Plating Total:</b>				<b>0.004771</b>	<b>1000000</b>	<b>19178.9609375</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.001132	1000000	4550.18017578		
<b>Internal Plating Total:</b>				<b>0.001132</b>	<b>1000000</b>	<b>4550.18017578</b>		
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.001132	750000	4550.18017578		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000377	250000	1515.38671875		
<b>Die Attach Total:</b>				<b>0.001509</b>	<b>1000000</b>	<b>6065.56640625</b>		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.009816	103000	39456.3320312		
		Bromine (Br)	40039-93-8	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.085294	895000	342847.21875		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.000000	0	0		
		Metal Hydroxide		0.000000	0	0		
		Carbon Black (C)	1333-86-4	0.000191	2000	767.742370605		
		<b>Encapsulation Total:</b>				<b>0.095301</b>	<b>1000000</b>	<b>383071.3125</b>
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000403	1000000	1619.89624023		
					<b>TOTAL MASS (g) :</b>	<b>0.248781</b>		